

1. Scope :

This specification applies to NPN silicon phototransistor chips,
Device No. ST-07024.

2. Structure :

- 2-1. Planar type.
- 2-2. Electrodes :
 - N (Collector) side : Gold alloy.
 - P (Base) side : Aluminum alloy.
 - N (Emitter) side : Aluminum alloy.

3. Size :

- 3-1. Chip size : 24 mils × 24 mils (0.610 mm × 0.610 mm).
- 3-2. Chip thickness : 10.6 ± 0.78 mils (0.270 ± 0.020 mm).
- 3-3. Active area : 17 mils × 17 mils (0.432 mm × 0.432 mm).
- 3-4. Pattern drawing : refer to the attached drawing.

4. Electrical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Collector-emitter Breakdown Voltage	BV_{CEO}	$I_C=100\mu A$ $I_B=0$	35			V
Emitter-collector Breakdown Voltage	BV_{ECO}	$I_E=100\mu A$ $I_B=0$	5			V
Collector dark current	I_{CEO}	$V_{CE}=20V$ $H=0mw/cm^2$			100	nA
Collector-emitter Saturation Voltage	$V_{CE(S)}$	$I_C=2mA$ $I_B=100\mu A$			0.2	V
Rise/fall time	t_R/t_F	$V_{CE}=5V$ $I_C=1mA$ $R_L=1000\Omega$		15/15		μs
Current gain	h_{FE}	$V_{CE}=5V$ $I_C=2mA$	200			
Collector-base Capacitance	C_{CB}	$f=1MHZ$ $V_{CB}=3V$		6.4		pF

h_{FE} RANK A : 1350-1890

